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# Microwave Ceramics

## Series/Type: A760

The following products presented in this data sheet are being withdrawn.

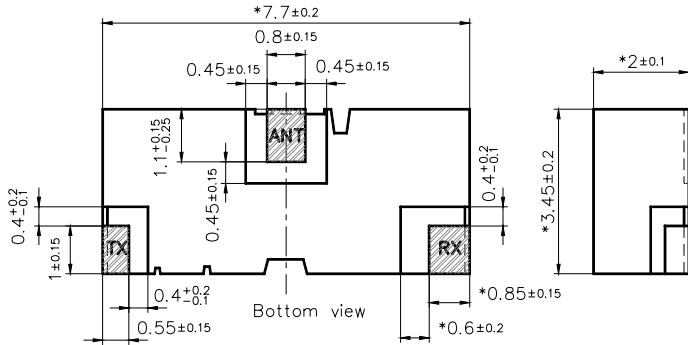
Ordering Code	Substitute Product	Date of Withdrawal	Deadline Last Orders	Last Shipments
B69967N2047A760	B39212B7646B310	2008-01-25	2008-09-30	2008-12-31

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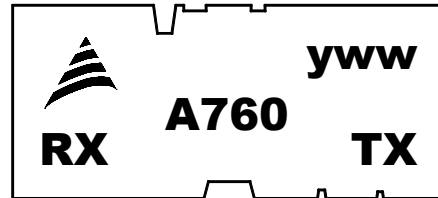
**7-Pole Duplexer for WCDMA**  
**Preliminary Data Sheet**

**B69967N2047A760**

**Component drawing**



**marking**

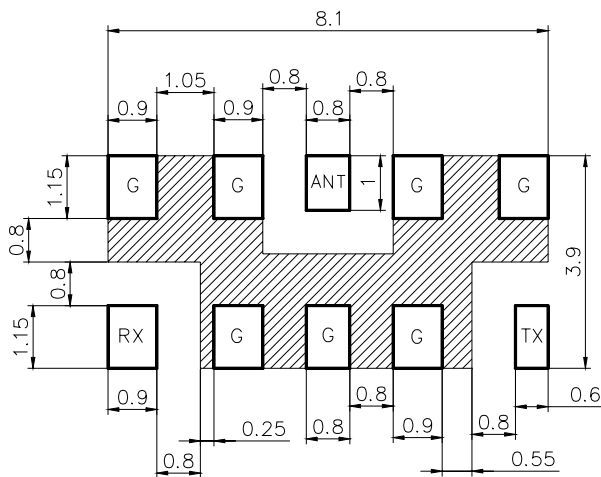





y= calendar year  
w= calendar week  
e.g.: 427= calendar year 2004,  
calendar week 27

\*depending in final pressing tool

View from below onto the solder terminals and view from beside

**Recommended footprint**



-  TX, RX, ANT, G solder pads
-  ground area below solder resist with vias to second ground layer
-  I/O connected to lines with an impedance of 50 Ohm
- Standard condition** FR4 material  
permutivity : 4.4  
preferred thickness : 0.3  
Vias:  $\varnothing 0.3\text{mm} / \text{mm}^2$   
For other thickness correlation might be necessary

- will be fixed acc. to final pressing tool

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Preliminary Data Sheet

Characteristics Receiver

		min.	typ.	max.	
Center frequency	$f_C$	-	2140	-	MHz
Insertion loss	$\alpha_{IL}$		1.3	1.6	dB
Passband	$B$	60			MHz
Amplitude ripple (peak - peak)	$\Delta\alpha$			0.9	dB
Standing wave ratio	SWR			1.9	
Impedance	$Z$		50		$\Omega$
Power	$P_{avg}$			0.8	W
Attenuation	$\alpha$				
	at DC to 1790 MHz	35 *			dB
	at 1790 to 1920 MHz	30			dB
	at 1920 to 1980 MHz	50			dB
	at 1980 to 2025 MHz	20			dB
	at 4030 to 4150 MHz	23 *			dB
	at 5950 to 6000 MHz	33 *			dB

\*depending on final pressing tool and final layout

Characteristics Transmitter

		min.	typ.	max.	
Center frequency	$f_C$	-	1950	-	MHz
Insertion loss	$\alpha_{IL}$		1.1	1.4	dB
Passband	$B$	60			MHz
Amplitude ripple (peak - peak)	$\Delta\alpha$			0.6	dB
Standing wave ratio	SWR			1.8	
Impedance	$Z$		50		$\Omega$
Power	$P_{max}$			1.0	W
Attenuation	$\alpha$				
	at DC to 1000 MHz	40			dB
	at 2110 to 2170 MHz	42			dB
	at 2400 to 2550 MHz	40			dB
	at 3840 to 3960 MHz	33 *			dB
	at 5760 to 5940 MHz	23 *			dB

\*depending on final pressing tool and final layout

Isolation Tx – Rx

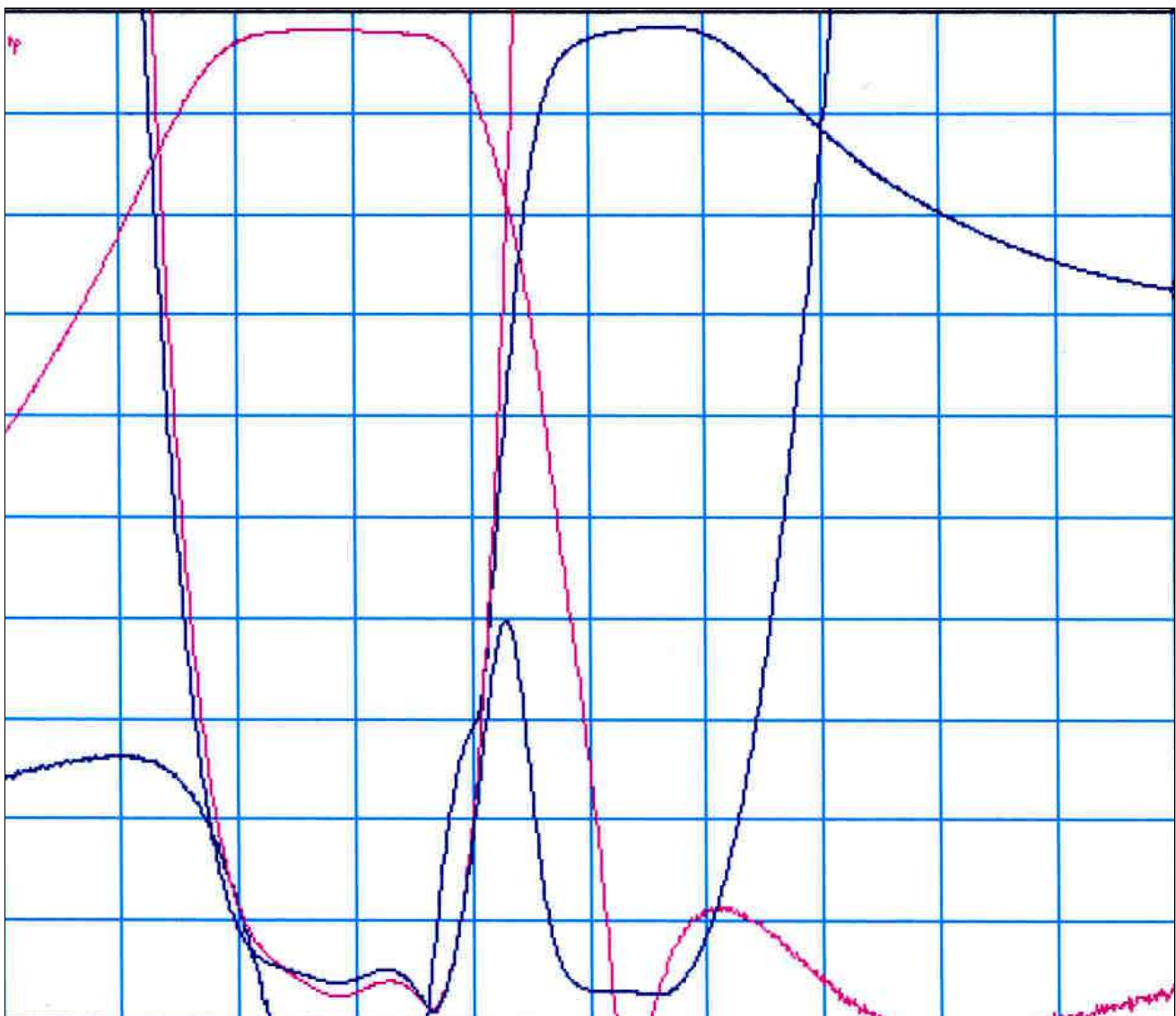
		min.	typ.	max.	
Attenuation	$\alpha$				
	at 1920 to 1980 MHz	50			dB
	at 2110 to 2170 MHz	45			dB



Maximum ratings

IEC climatic category (IEC 68-1)	- 40/+ 90/56	
Operating temperature	$T_{op}$ -40 / +85	°C

Typical passband characteristic



**7-Pole Duplexer for WCDMA**  
**Preliminary Data Sheet**

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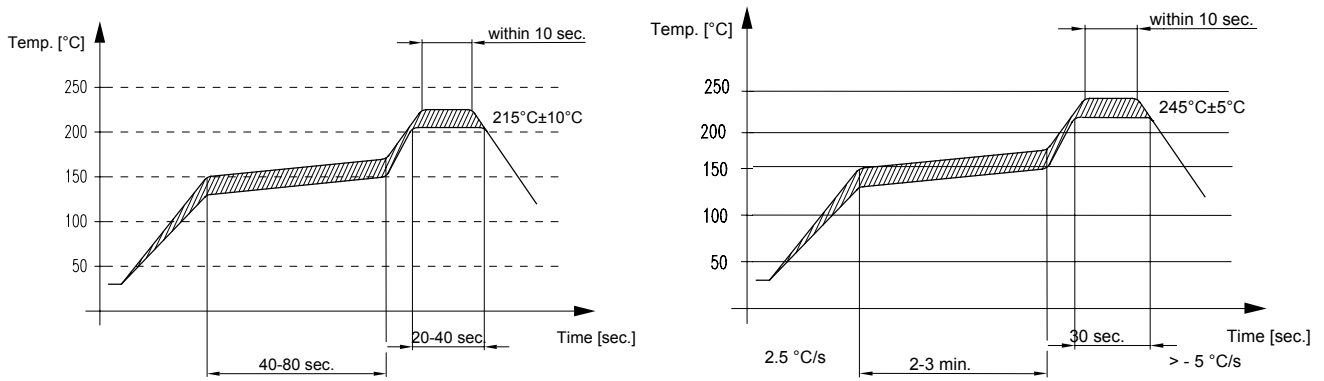
**Processing information**

- Wettability to IEC 68-2-58:  $\geq 75\%$  (after aging)

**Soldering Requirements**

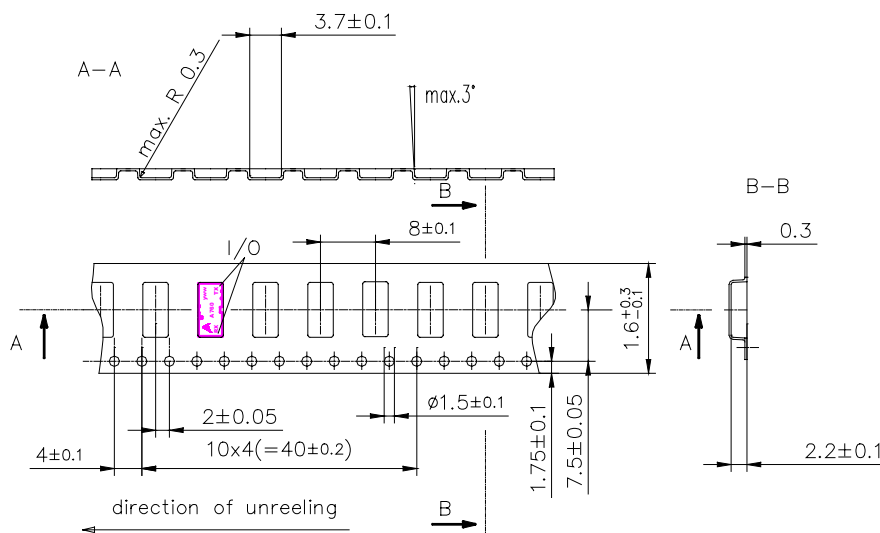
	Profile for eutectic SnPb solder paste	Profile for leadfree solder paste	
Soldering type	reflow	reflow	
Maximum soldering temperature (measuring point on top surface of the component)	235 (max. 2 sec.) 225 (max. 10 sec.)	260 (max. 2 sec.) 250 (max. 10 sec.)	°C °C

Recommended soldering conditions (infrared):



**Delivery mode**

- Blister tape acc. to IEC 286-3, polyester, grey
- Pieces/tape: 3000



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